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CLAIMS

- 5 (1) A method for preventing the occurrence of a tin whisker, characterized in that ordinary tin plating is provided on a base metal, after which a thin lead film of 0.05 μm or more is formed on a surface thereof.
- 10 (2) A method for preventing the occurrence of a tin whisker according to claim 1, characterized in that the thin lead film is formed by electroplating, electroless plating, vapor deposition, or sputtering.
- 15 (3) A method for preventing the occurrence of a tin whisker according to claim 1, characterized in that a region having a high lead concentration is formed as the thin lead film by ion implantation, or diffusion.
- 20 (4) A method for preventing the occurrence of a tin whisker according to claim 1 or 2, characterized in that a thin film of a lead-tin alloy containing 5% or more of lead is formed as the thin lead film.